

# *Long term annealing of neutron irradiated detectors evaluated at LHC operational temperatures*

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**8 RD50 Collaboration Workshop  
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# *Technotest*

## **Goal of the project:**

*Finding correlations and comparison of radiation hardness with respect to:*

Type of Si

Processing

Radiation

characteristics of heavily irradiated detectors

# *Technotest*

## *Participants*

### *Detector processing:*

- ◆ Ioffe Physico-Technical Institute (PTI)  
+ Research Institute of Material Science and Technology (RIMST)
- ◆ BNL
- ◆ Helsinki Institute of Physics (HIP)

### *Irradiation:*

- ◆ CERN (protons 24 GeV/c)
- ◆ Iosef Stefan Institute, Ljubljana (neutrons 1 MeV)

### *Evaluation*

- ◆ Ioffe Physico-Technical Institute
- ◆ BNL
- ◆ HIP
- ◆ Iosef Stefan Institute
- ◆ Glasgow University

## *Status of the work*

### *Experiments carried out:*

- ✓ detectors processed at three institutions
- ✓ irradiated by 1 MeV neutrons,  $F_n = 1 \cdot 10^{10} - 5 \cdot 10^{15} \text{ cm}^{-2}$
- ✓ irradiated by 24 GeV/c protons,  $F_p = 1 \cdot 10^{14}$  and  $1 \cdot 10^{15} \text{ cm}^{-2}$

**1 MeV neutrons:** *pres. 5 RD50 Workshop, Florence*  
**I-V characteristics, TCT signal**

**24 GeV protons:** *pres. 7 RD50 Workshop, CERN*  
**SCSI in detectors from MCZ Si;  $V_{fd}$  and  $N_{eff \text{ in}}$  in long term annealing**

### *Current study in 2006*

**1 MeV neutrons: studies of annealing (initial stage)**

- ✓ detectors processed from MCZ and FZ n-type Si
- ✓ annealing at 80°C

## *Experimental samples*

$F_n$ (cm <sup>-2</sup> )	FZ		CZ		
5E+13	PTI-n1-b11	HIP-w-57	PTI-Cz-c12	HIP-CZ-34	BNL-n-131
5E+14	PTI-n2-c13	HIP-w-7	PTI-Cz-d11	HIP-Cz-66	BNL-Cz-98

Resistivity, k $\Omega$ ·cm

n-Si FZ: 4-6

n-Si MCZ: 1

## *Manufacturing procedure*

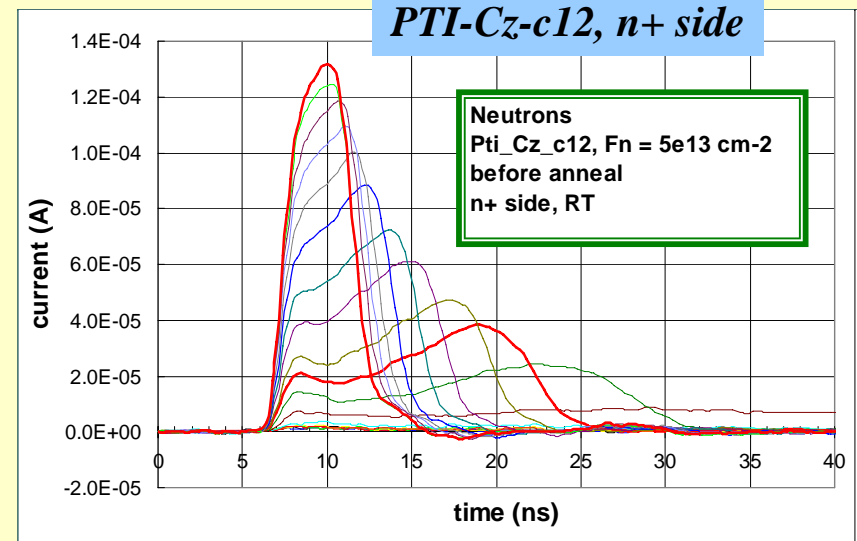
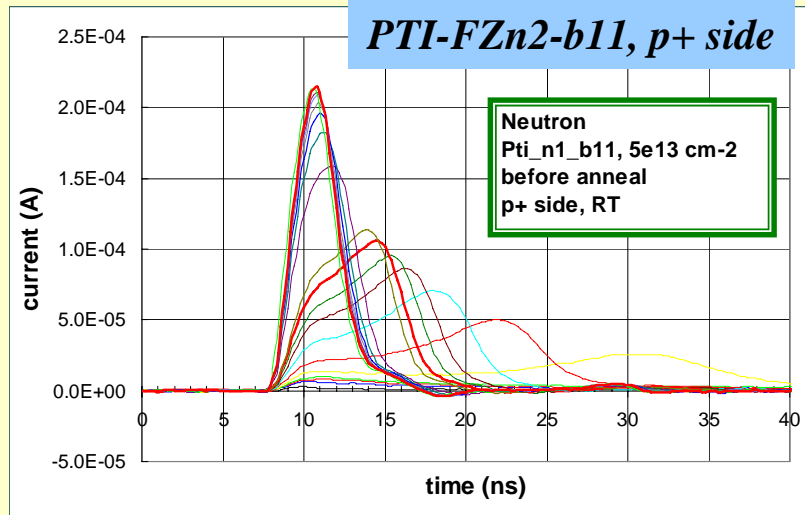
	PTI	BNL	HIP
Oxidation	1100C/6h	1100C/6h	<b>done after implantation</b>
p+	50 keV/ 3e14 cm-2	45 keV/2e14cm-2	20 keV/1e15cm-2
n+	80 keV/9e14 cm-2	80 keV/6e14cm-2	70 keV/1e15cm-2
Annealing	700C/40min	700C/30min	1100/4h
Al sintering	430C/7min	430C/5min	<b>370C/40min (no TD)</b>

# *Experimental*

- ✓ annealings: 80°C, steps with variable time
- ✓ TCT using 840 nm laser pulse generation of free carriers, p+ side, n+ side
- ✓ **Current pulse response is measured at RT and -15°C (ATLAS)**
- ✓ **All measurements: range of bias voltage 20/50-900 V**

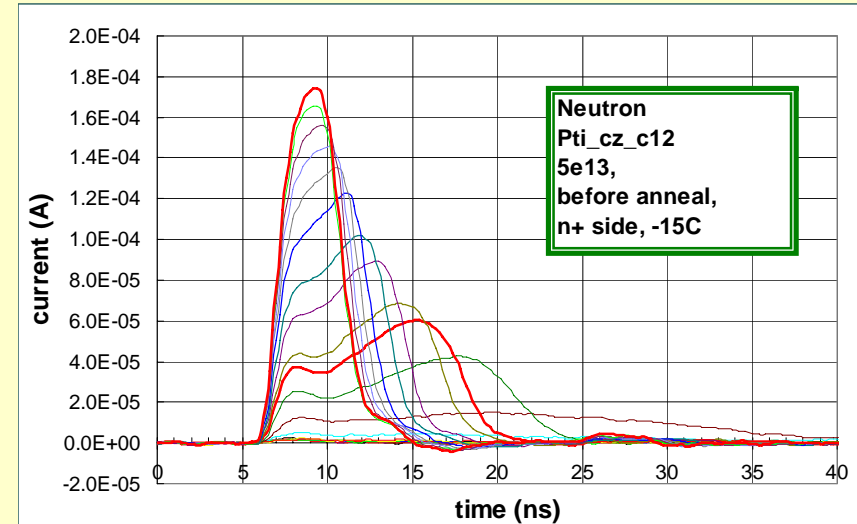
# Current pulse response, n-Si, $F_n = 5 \cdot 10^{13} \text{ cm}^{-2}$

Before annealing



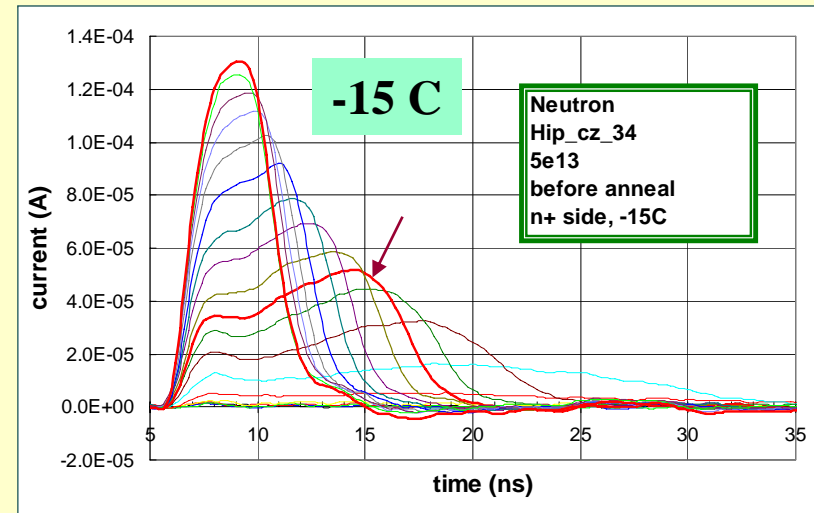
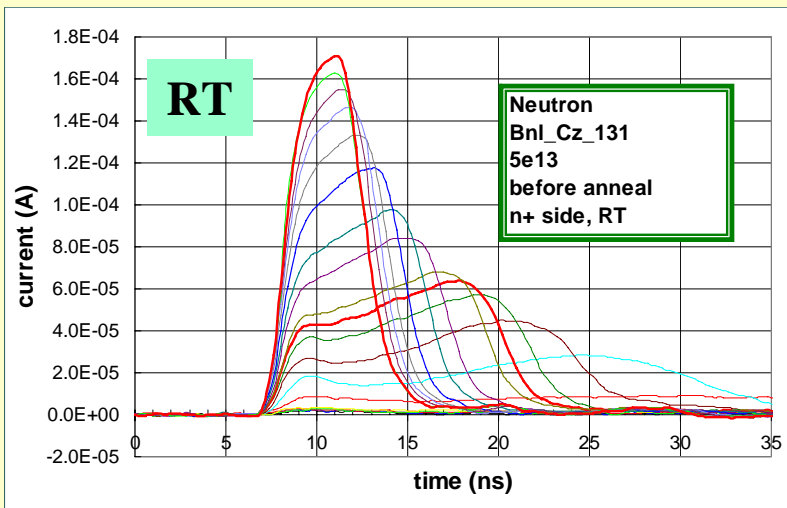
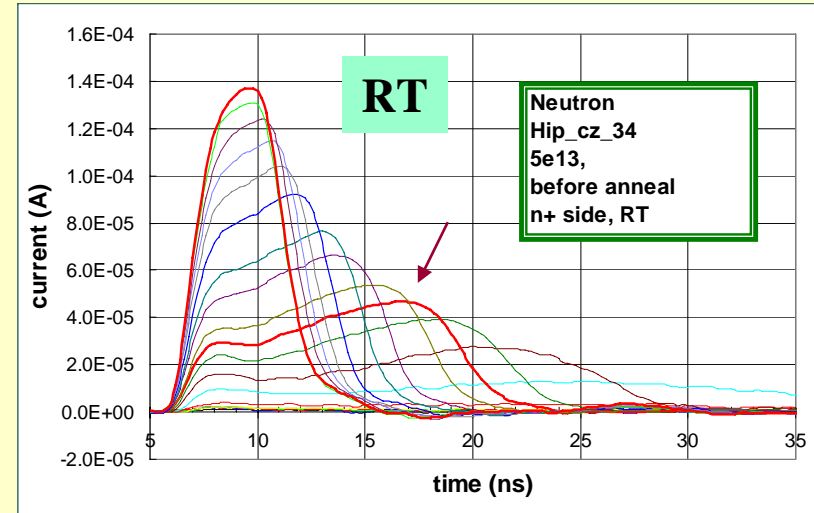
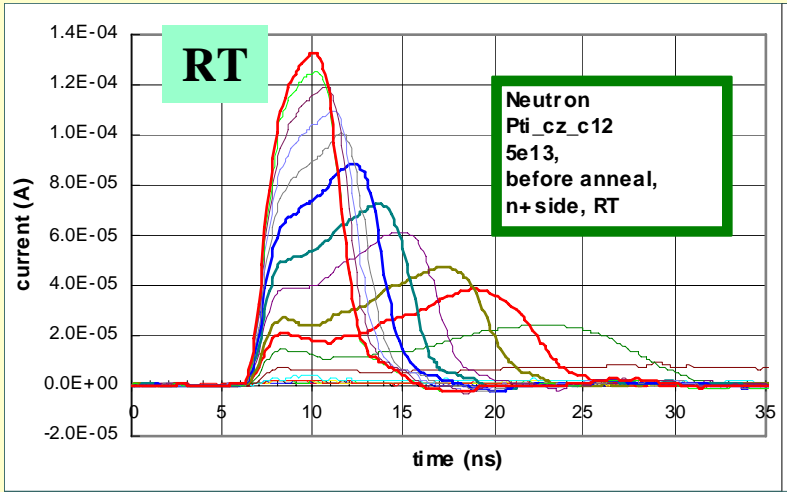
**Before annealing:**  
**FZ Si: SCS (-SC)**  
**MCZ Si: no SCS (all samples)**  
**- evaluation of response from**  
**n+ side, hole collection**

V: 10-900 V

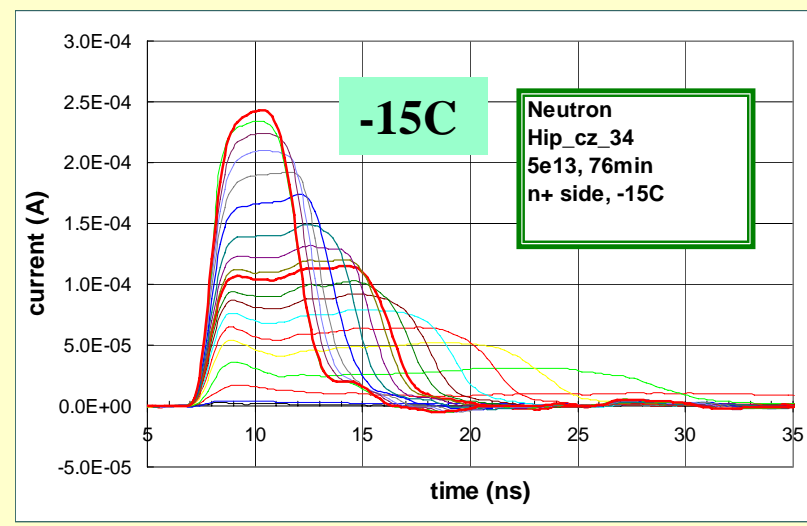
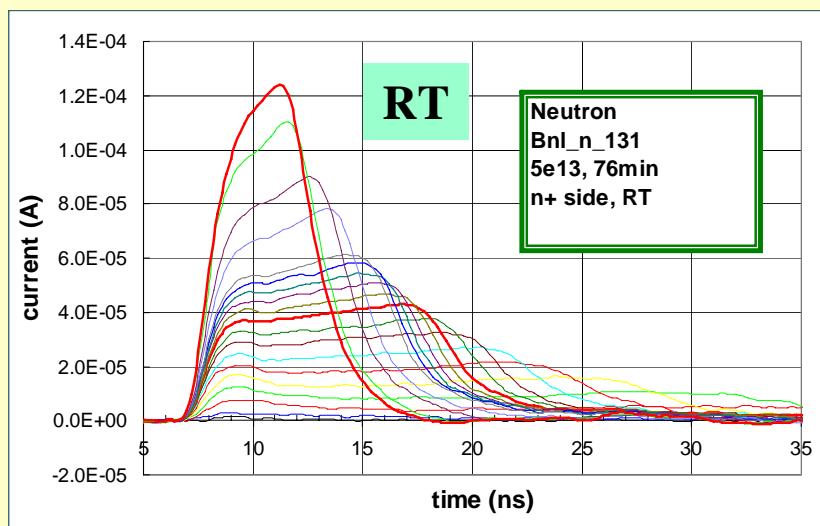
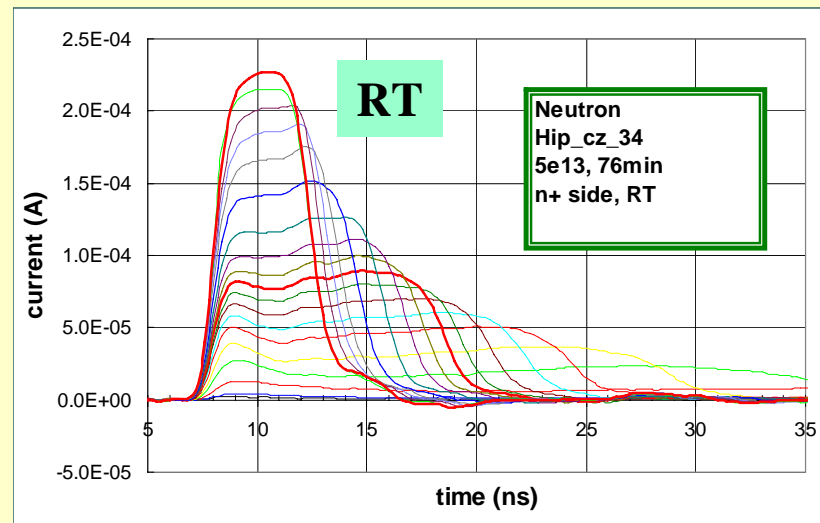
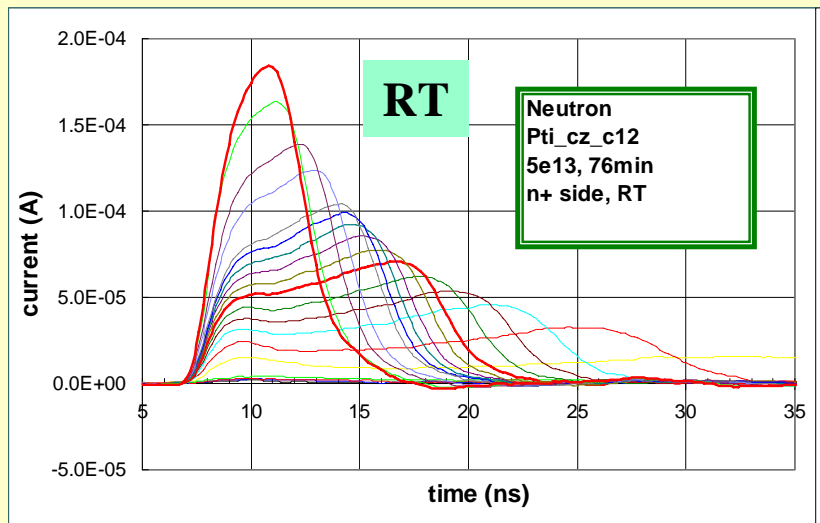




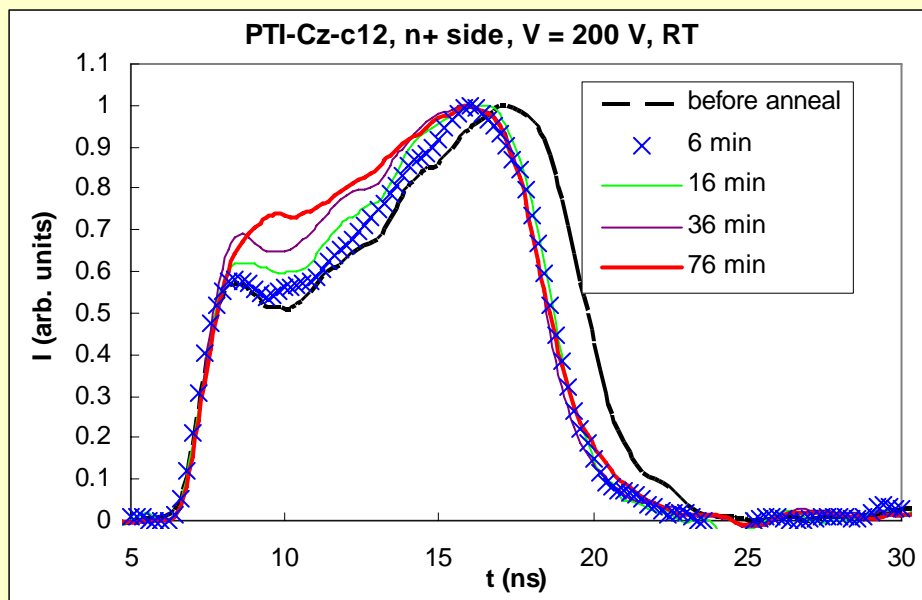
# MCZ Si, $F_n = 5 \cdot 10^{13} \text{ cm}^{-2}$ : different processing



$$F_n = 5 \text{ e}13 \text{ cm}^{-2}, t_{ann} = 76 \text{ min}$$



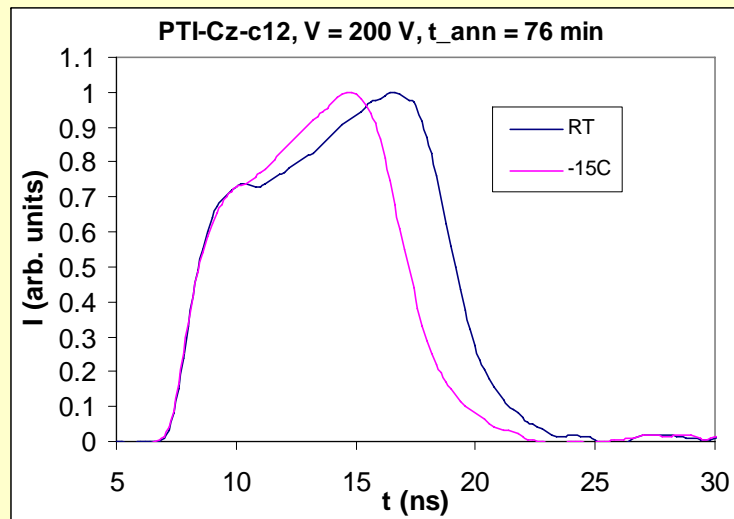
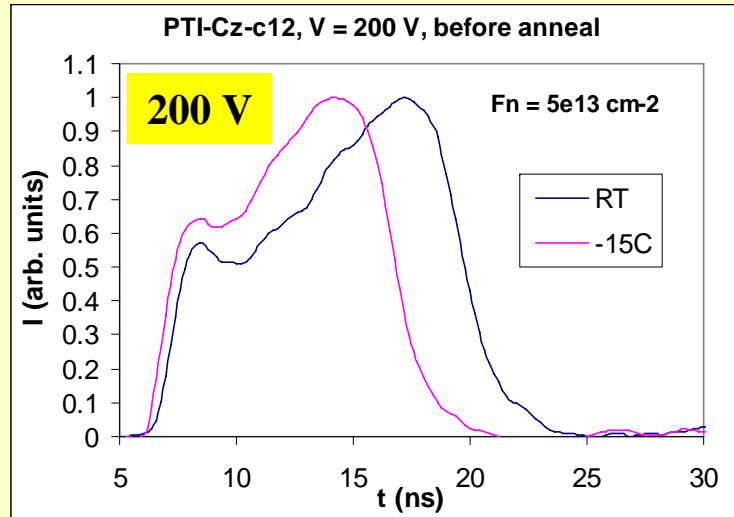
*Evolution of response under annealing,  
MCZ Si,  $F_n = 5 \cdot 10^{13} \text{ cm}^{-2}$ ,  $V = 200 \text{ V}$ , hole collection*



$$i(t) = \frac{Q_0 \mu E}{d} e^{-t/\tau_{\text{eff}}}$$

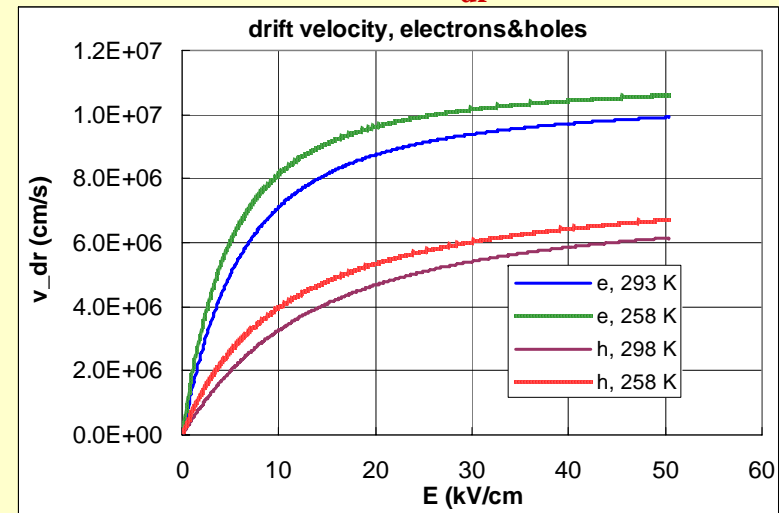
**RT: detector is fully depleted,  
+ $N_{\text{eff}}$  decreases –  
E becomes more uniform**

## Evolution of response under annealing



$$i(t) = \frac{Q_o v_{dr}}{d} e^{-t/\tau_{eff}}$$

**Dependence of  $v_{dr}$  vs. E and T**



**Pulse width: depends on  $v_{dr}(T)$**

**Difference:**

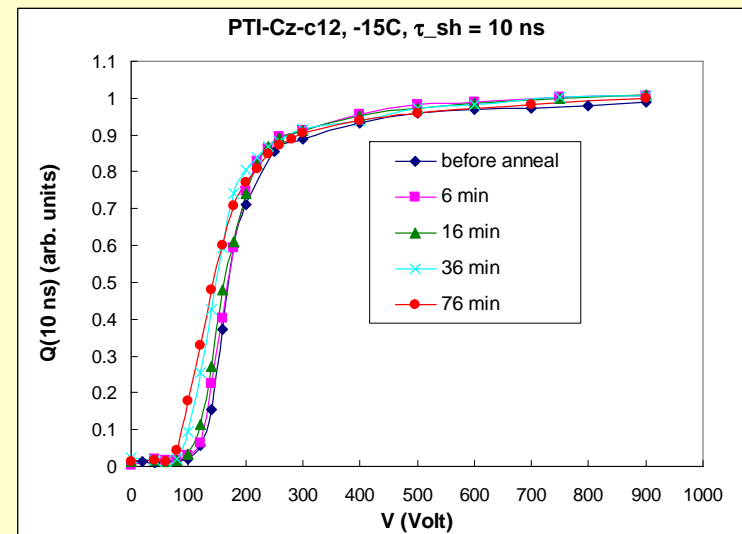
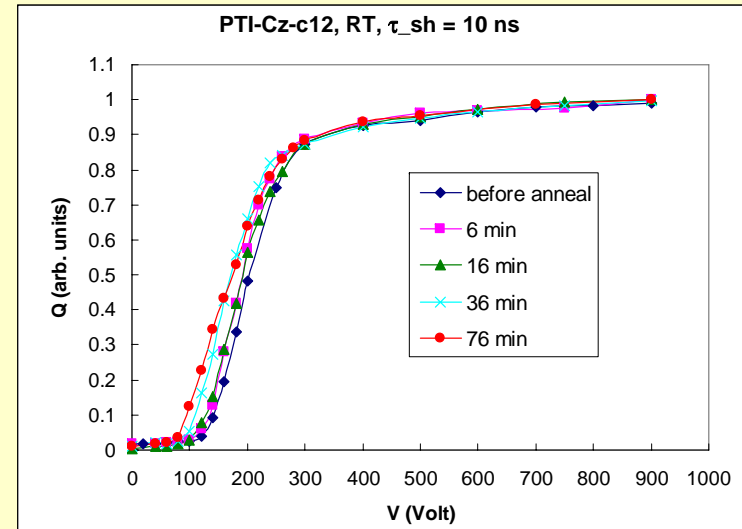
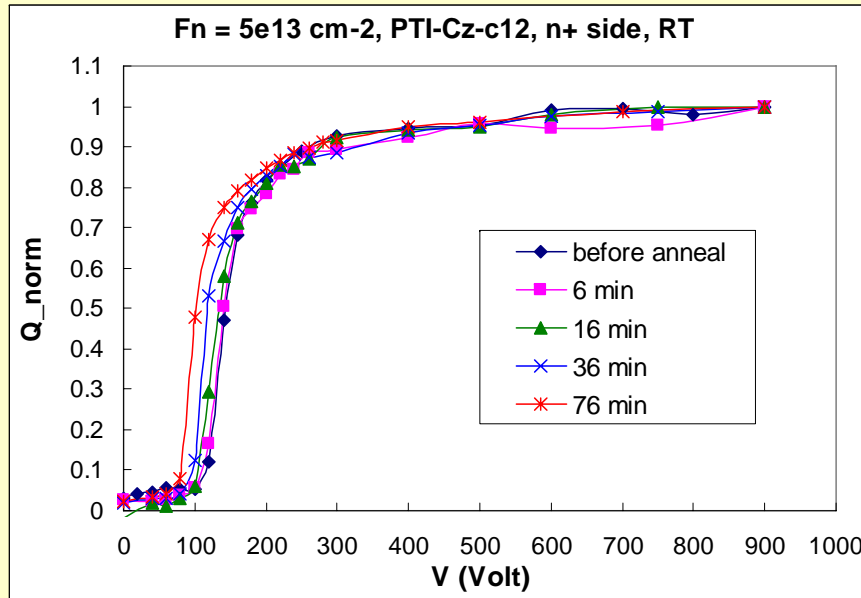
**Low E: e – 30%, h – 50%**

**High E: e, h – 10%**

$Q$  vs.  $V$  and  $\tau_{sh}$ , MCZ n-Si,  $F_n = 5 \cdot 10^{13} \text{ cm}^{-2}$

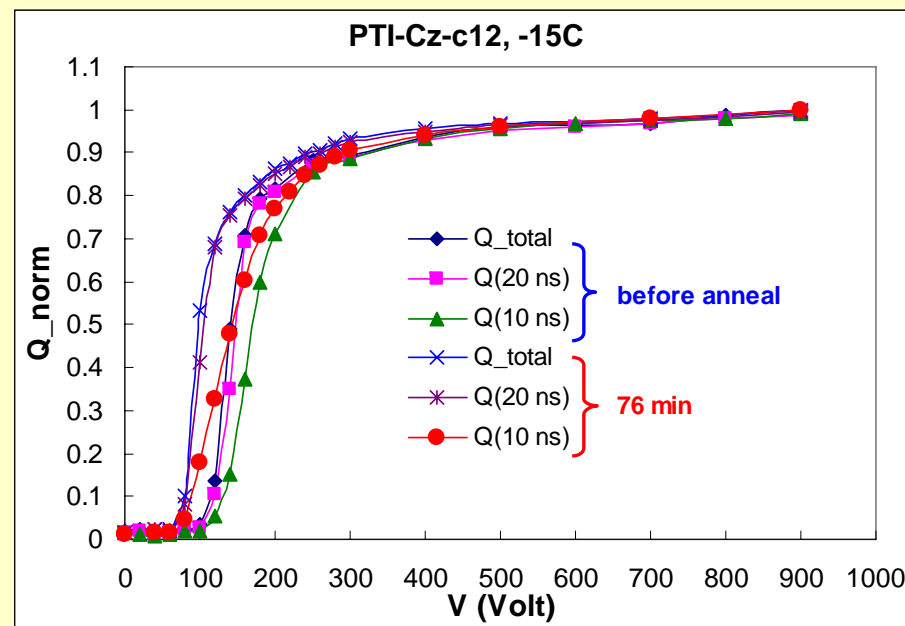
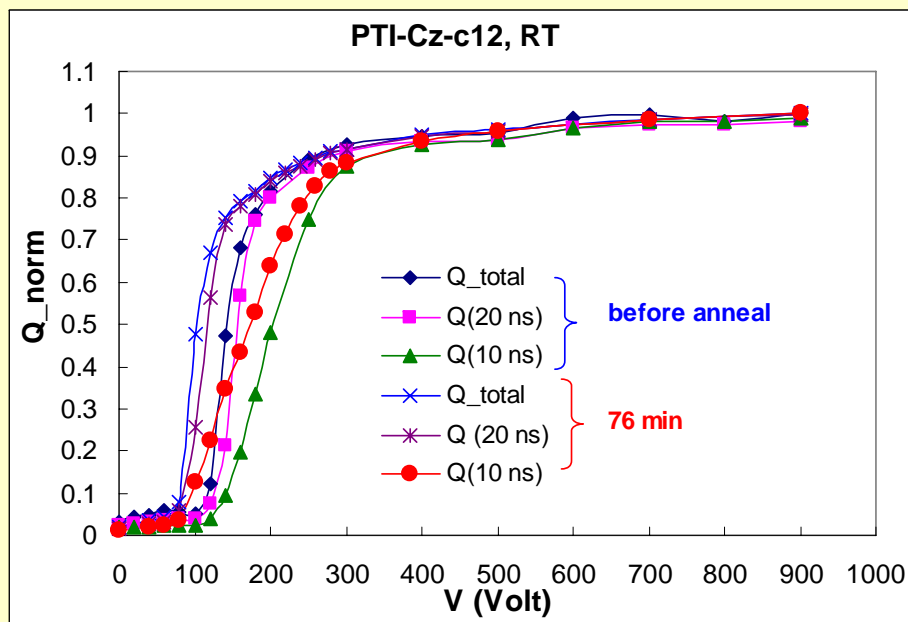
$\tau_{sh} = 10 \text{ ns}$

Total charge, RT



$\tau_{sh}$  – shaping time

$Q$  vs.  $V$  and  $\tau_{sh}$ , MCZ  $n$ -Si,  $F_n = 5 \cdot 10^{13} \text{ cm}^{-2}$

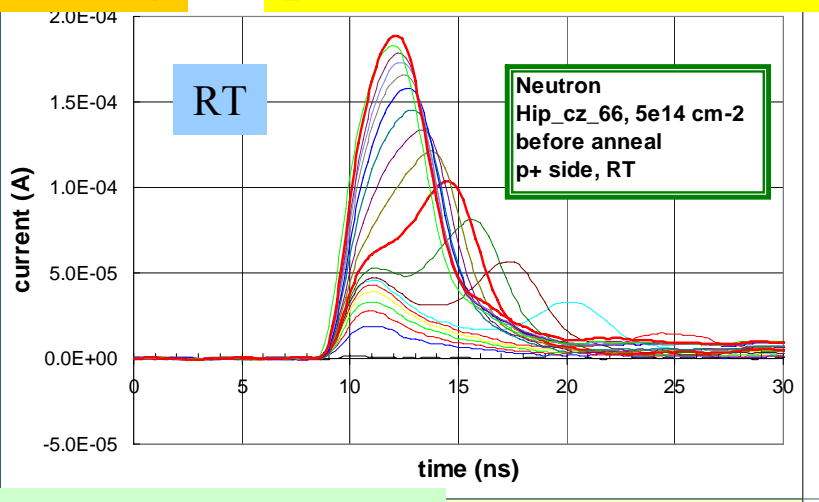
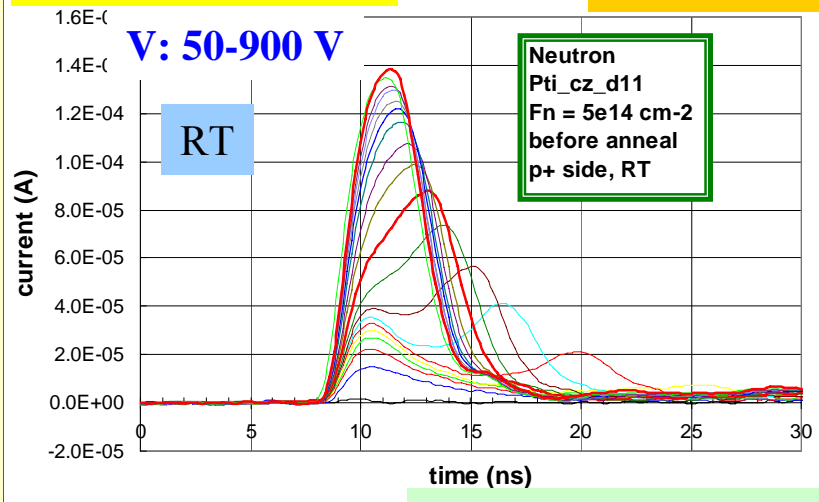


# Current pulse response, MCZ n-Si, $F_n = 5 \cdot 10^{14} \text{ cm}^{-2}$

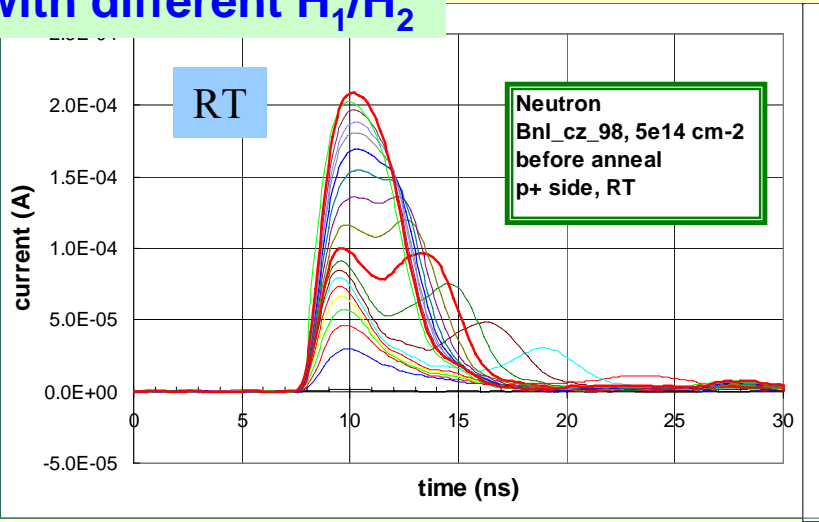
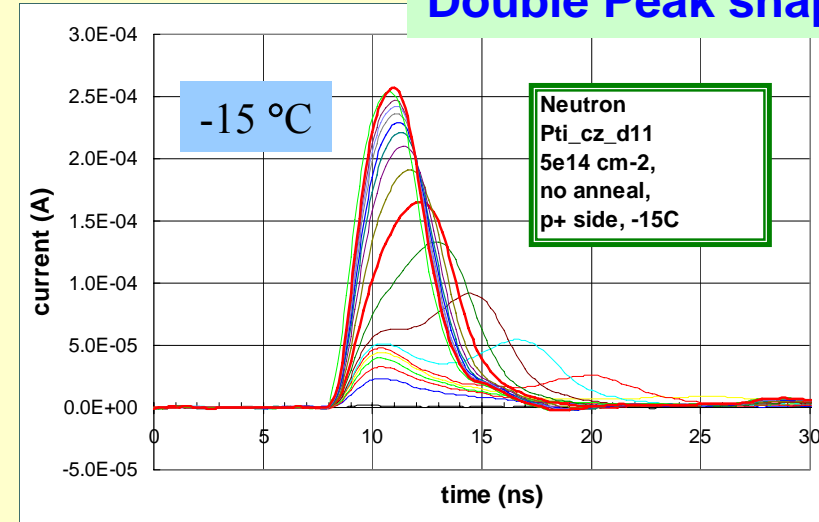
**Before annealing**

**Different processing**

**p+ side, electron collection**



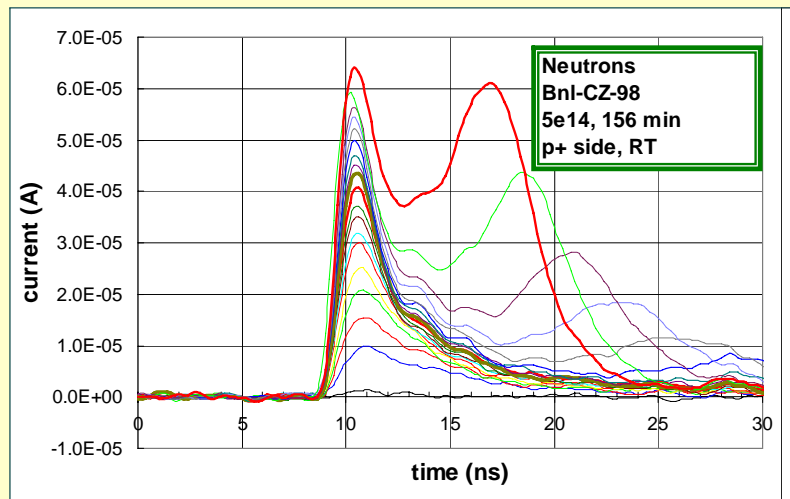
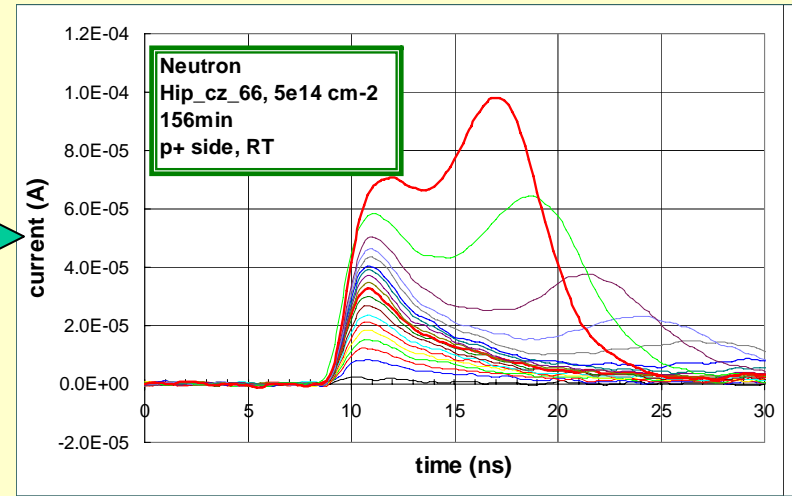
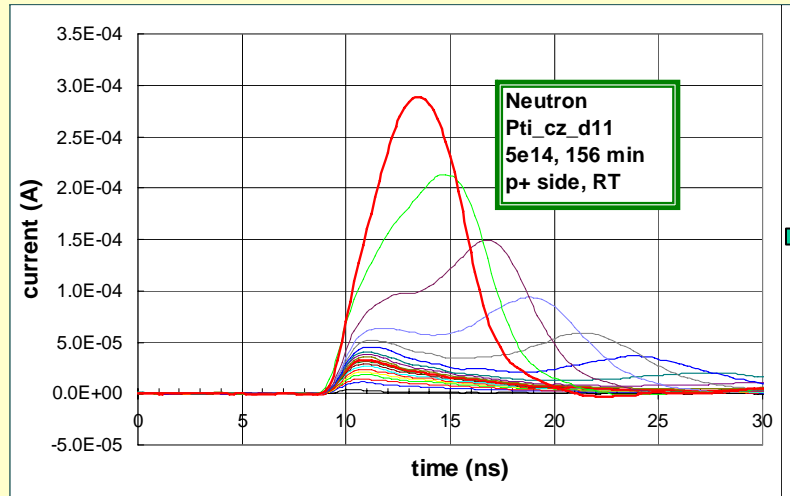
**Double Peak shape with different  $H_1/H_2$**



**SCSI for all detectors, at RT and -15 °C**

*E. Verbitskaya et al., 8 RD50 Workshop, Prague, June 25-28, 2006*

**$F_n = 5 \text{ e}14 \text{ cm}^{-2}, t_{ann} = 156 \text{ min, RT}$**

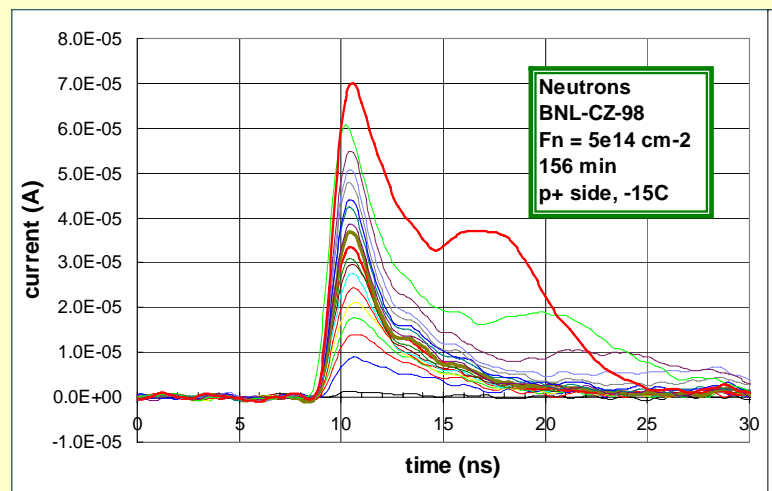
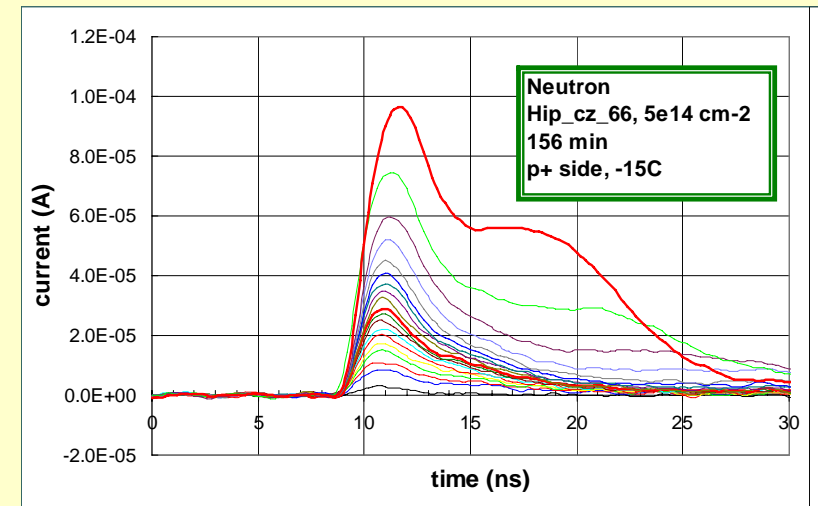
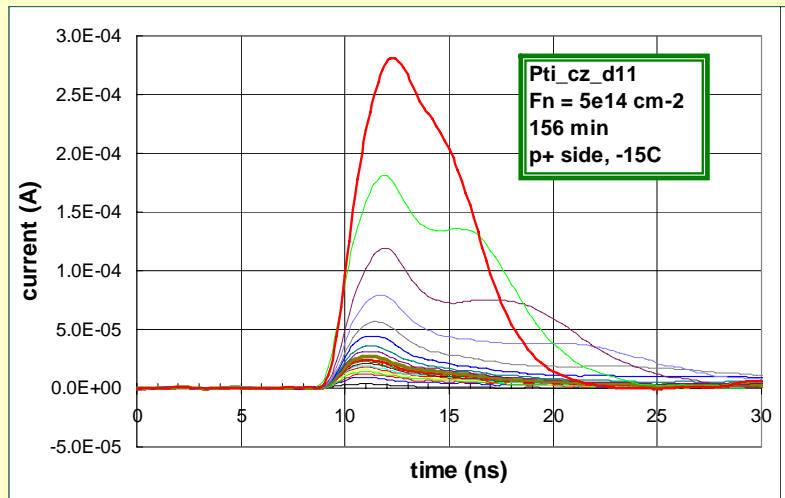


**$H_1/H_2$  ratio in DP is different:  
 $E(x)$  is different**

**Practical aspect:  
 $t_{coll}$  is sensitive to technology**



**$F_n = 5e14 \text{ cm}^{-2}$ ,  $t_{ann} = 156 \text{ min}$ ,  $-15^\circ\text{C}$**

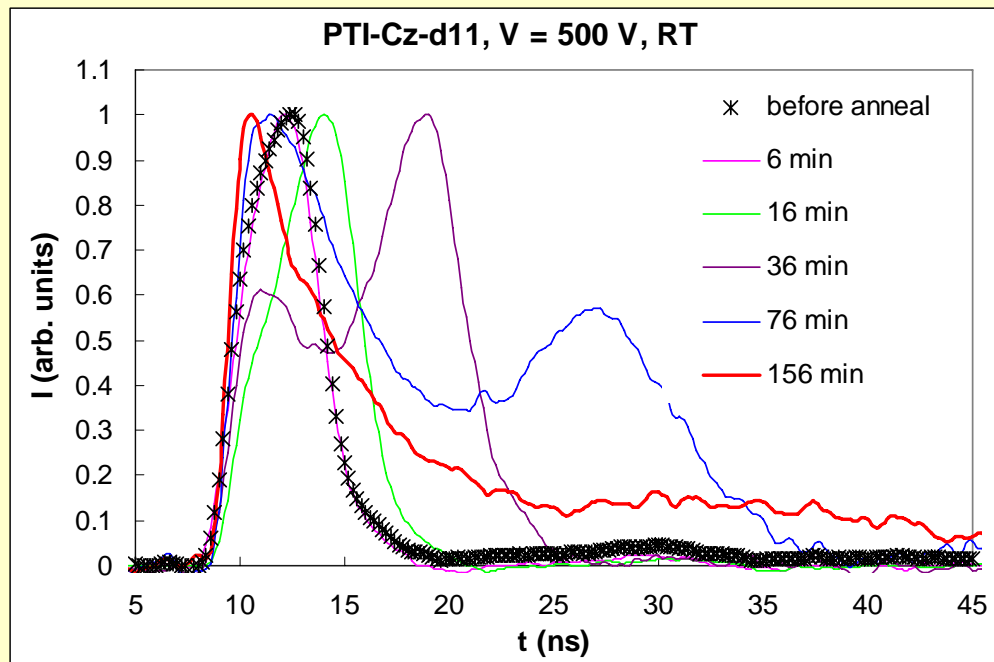


**At  $-15^\circ\text{C}$ :**  
**Pronounced DP with**  
 **$H_1/H_2 > 1$  even at 900 V**  
**- reduction of E at n+ side**

## *Evolution of response under annealing*

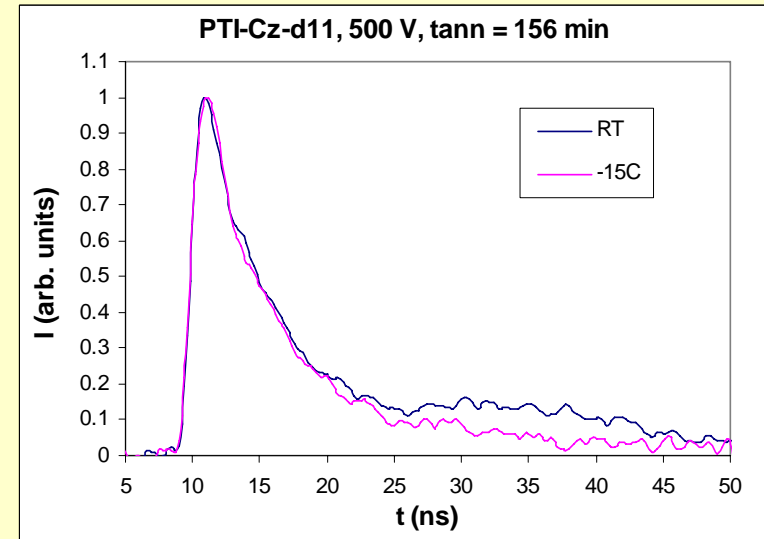
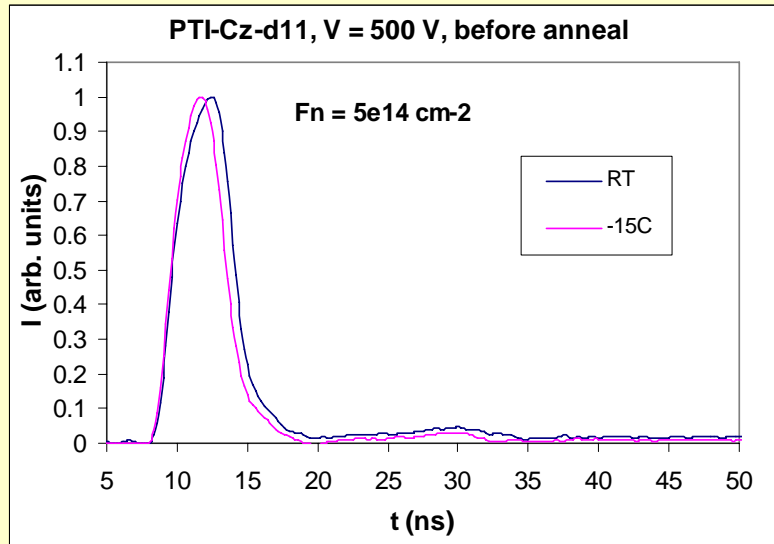
*MCZ Si,  $F_n = 5 \cdot 10^{14} \text{ cm}^{-2}$   $V = 500 \text{ V}$ , RT*

Electron collection



**E(x) changes from full depletion to partial depletion at RT and  $-15^\circ\text{C}$**

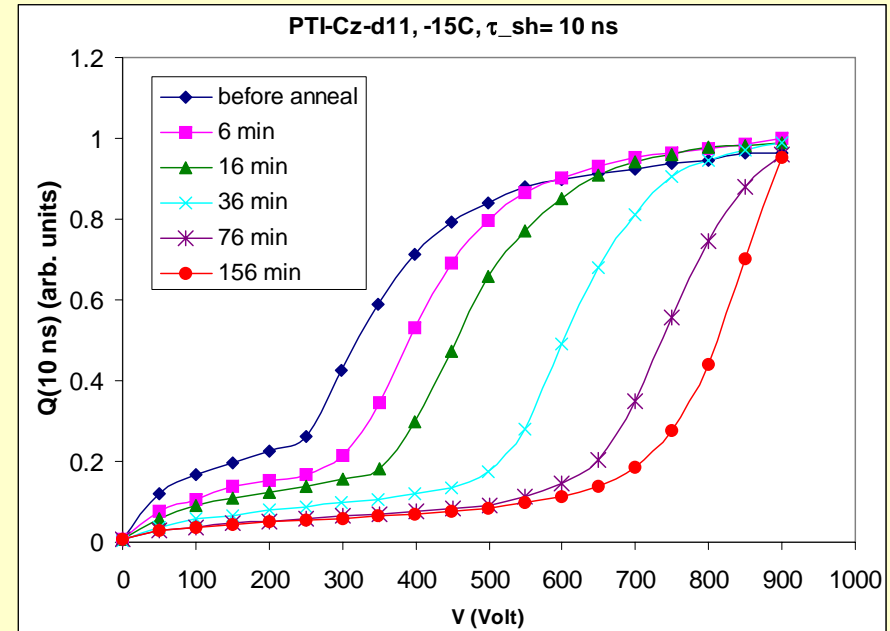
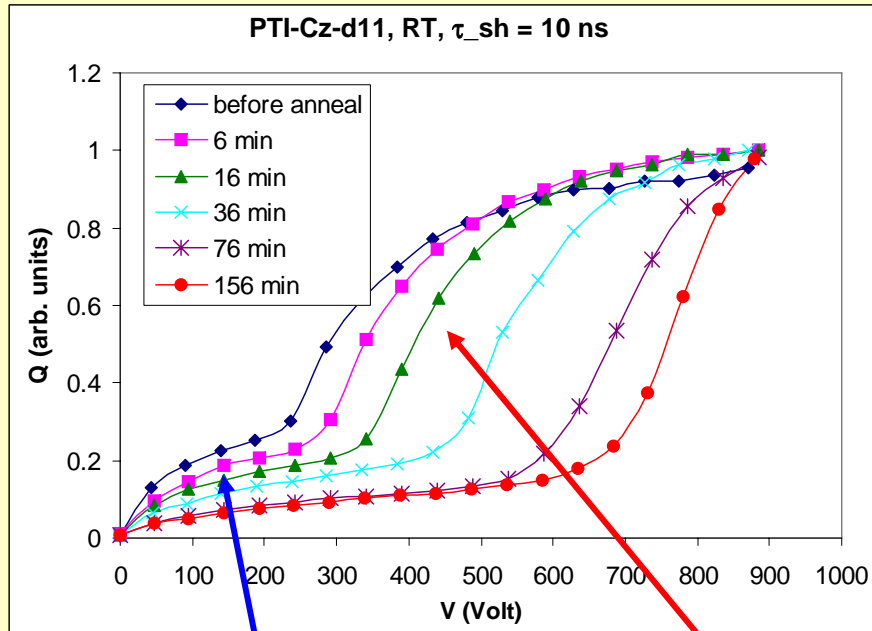
*Evolution of response under annealing,  
MCZ Si,  $F_n = 5 \cdot 10^{14} \text{ cm}^{-2}$ ,  $V = 500 \text{ V}$*



$\tau$  is the same at RT and  $-15^\circ\text{C}$   
 $\tau = 6 \text{ ns}$   
- lowest value!

# *Q vs. V under annealing*

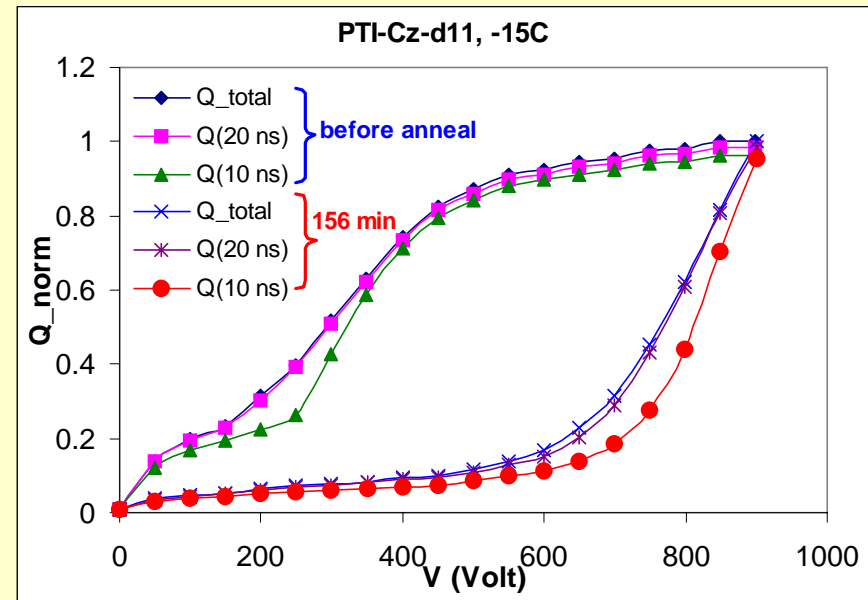
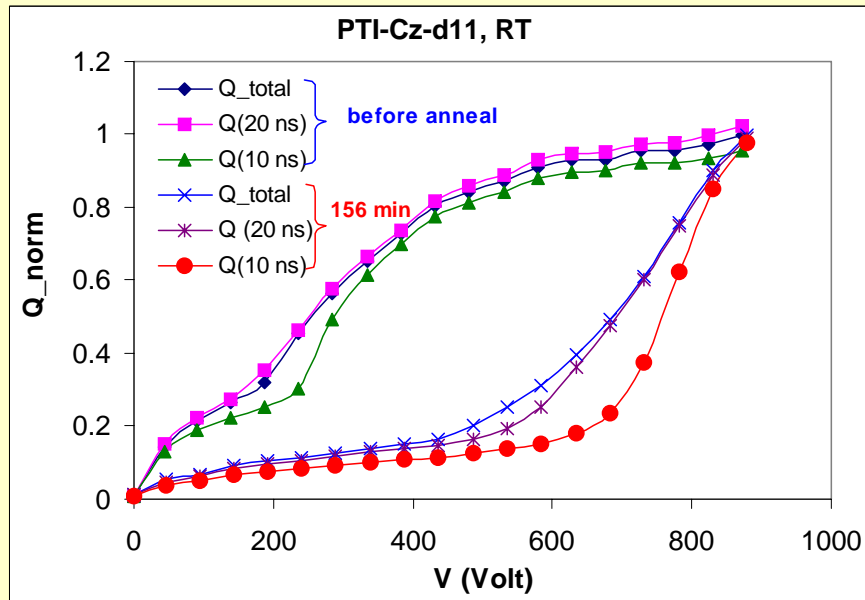
*MCZ n-Si,  $F_n = 5 \cdot 10^{14} \text{ cm}^{-2}$*



Single peak ↑

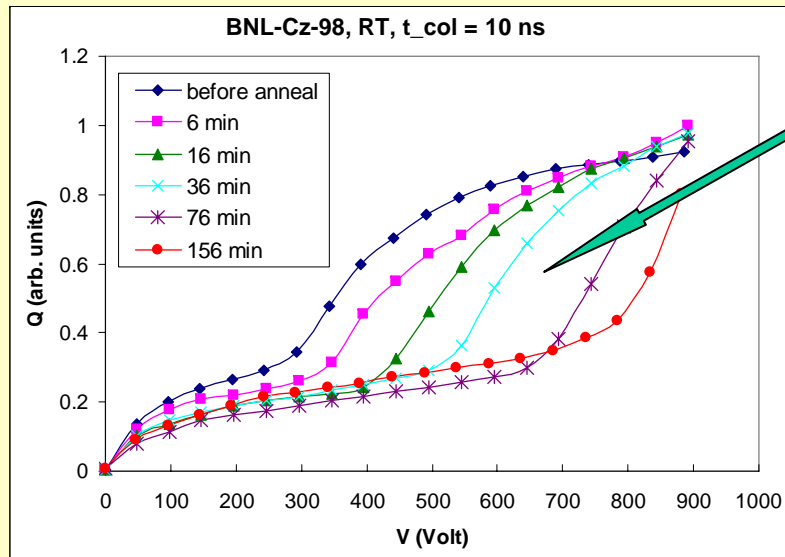
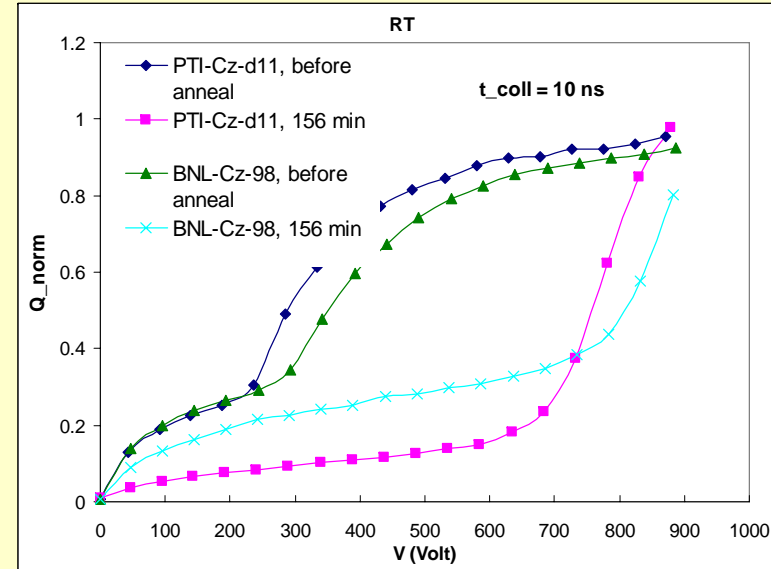
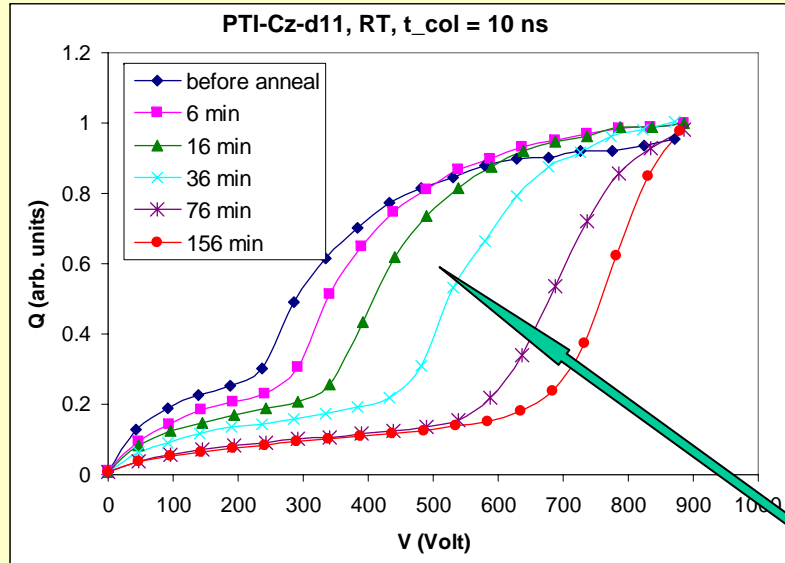
Double peak ↑

## $Q$ vs. $V$ and $\tau_{sh}$ at RT and $-15^\circ\text{C}$



- Visible CCE reduction at  $\tau_{sh} = 10\text{ ns}$
- Reduction is less at  $-15^\circ\text{C}$  ( $v_{dr}$ )

# Different processing, $Q$ vs. $V$ at RT

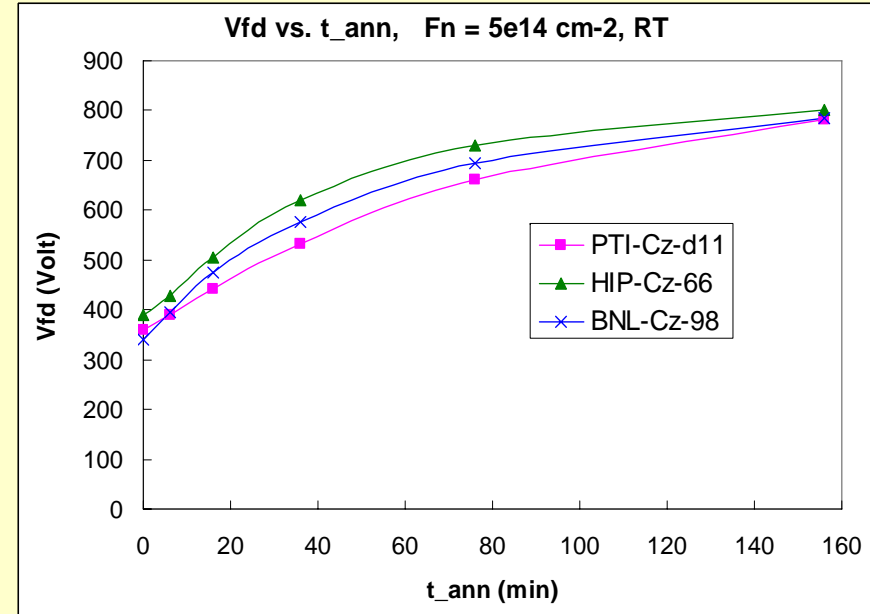
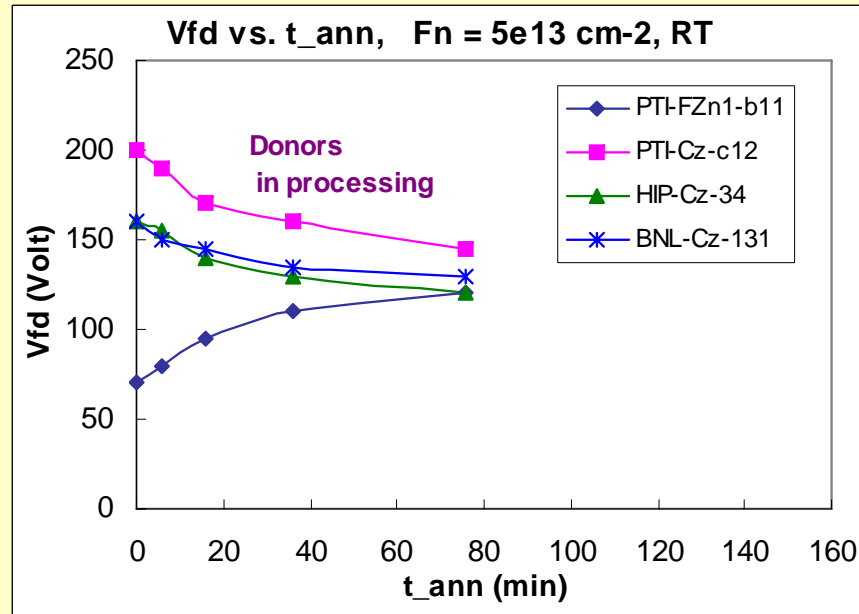


Difference in  $H_1/H_2$

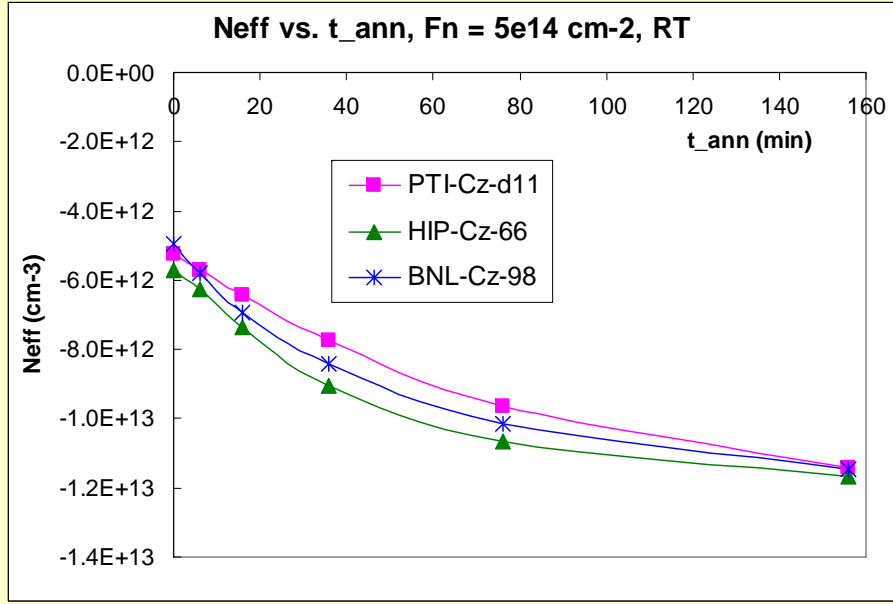
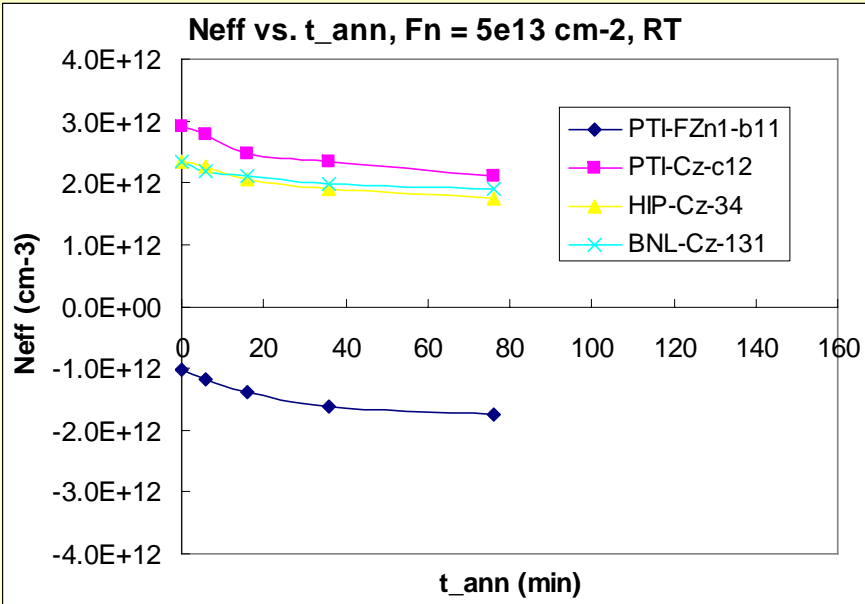
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Prague, June 25-28, 2006*

*$V_{fd}$  and  $N_{eff}$  evaluated from pulse response  
initial annealing stage*

$V_{fd}$



# *$N_{eff}$ evaluated from pulse response*



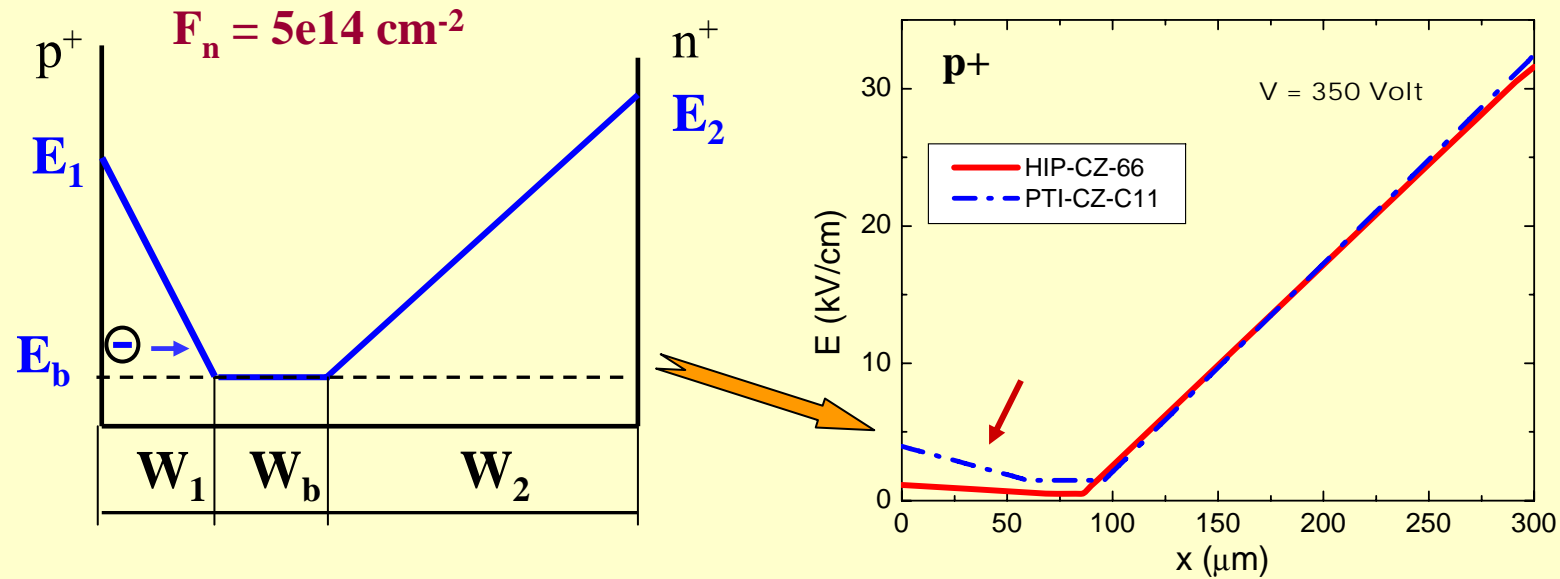
## Effective macroscopic parameters:

▼ **As-irradiated MCZ Si detectors:**  
**5e13 cm<sup>-2</sup>: sensitive to processing**  
**5e14 cm<sup>-2</sup>: no sensitivity**

▼ **Annealing ≤160 min:**  
**reduces sensitivity**



## Reconstruction of $E(x)$ from DP response



	HIP-CZ-66	PTI-CZ-C11
tau_e (ns)	4	5
Neff1 (cm-3)	1.41E+11	1.09E+12
Neff2 (cm-3)	9.46E+12	9.51E+12
E_b (V/cm)	500	1500

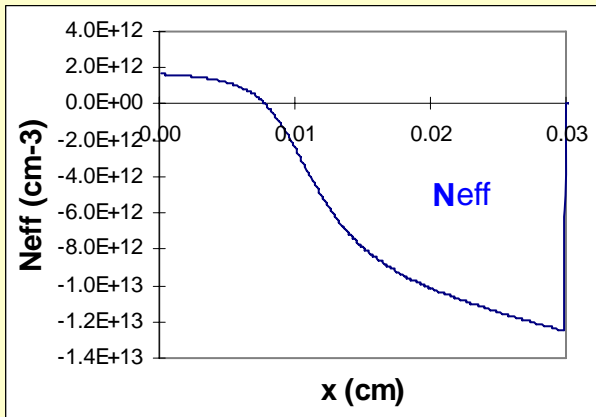
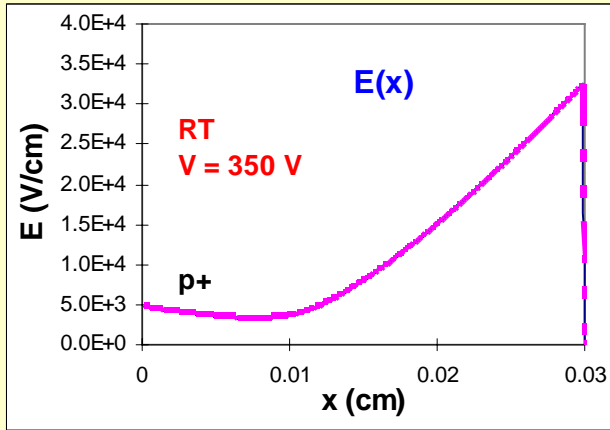
**Electric field gradient  $dE/dx$  and  $N_{\text{eff}}$  in the region adjacent to  $p^+$  contact are different and sensitive to detector processing**



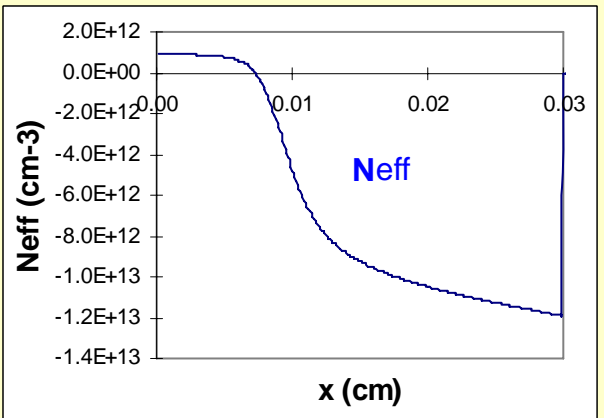
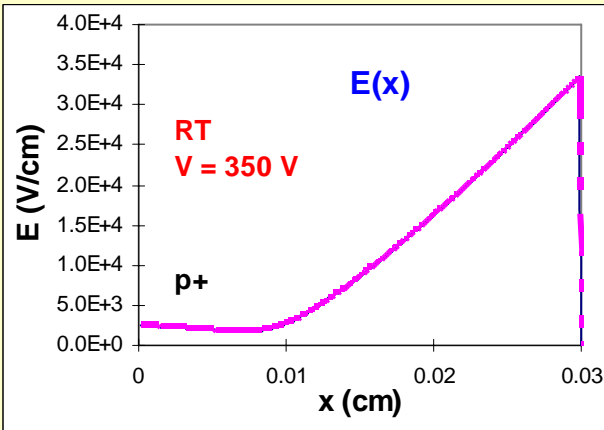
**difference in balance of DDs and DAs induced by radiation**

# $E(x)$ reconstruction

PTI-Cz-d11



HIP-Cz-66



		PTI-Cz-d11	HIP-Cz-66
<b>MGD</b>	<b><math>E_v + 0.48</math> eV</b>	<b>2.50E+15</b>	<b>1.40E+15</b>
<b>MGA</b>	<b><math>E_c - 0.52</math> eV</b>	<b>1.00E+15</b>	<b>7.50E+14</b>

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## Conclusions

### Detectors from n-type MCZ silicon irradiated by 1MeV neutrons

- ✓  $F_n = 5 \cdot 10^{13} \text{ cm}^{-2}$ 
  - Space Charge (+)
  - Insignificant difference of pulse response before and after annealing
- ✓  $F_n = 5 \cdot 10^{14} \text{ cm}^{-2}$ 
  - Space Charge (-)
  - DP current pulse shape dominates
  - $H_1/H_2$  is affected by technology and changes under annealing
  - Annealing reduces difference in effective macroscopic parameters

*Protons,  $F_p = 1 \cdot 10^{15} \text{ cm}^{-2}$ : influence of technology is still observed!*

**RT  $\rightarrow$   $-15 \text{ }^\circ\text{C}$ :**

- ✓ **trapping lifetime is the same**
- ✓ **reduction of E at n+ side**
- ✓ higher drift velocity, reduction of current and dissipated power